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Product Change Notification - CYER-21JXDZ485

Date: 03 Aug 2011

Product Category: Memory

Device Family:

Notification subject: CCB 1072: Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
See attachments of affected catalog part numbers (CPN) labeled as…
PCN_CYER-21JXDZ485_Affected_CPN.xls
PCN_CYER-21JXDZ485_Affected_CPN.pdf

Description of Change:
Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.

Pre Change:
8390A die attach

Post Change:
8006NS die attach

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability

Change Implementation Status:
In Progress

Estimated First Ship Date:
October 28, 2011 (date code: 1144)

NOTE: Please be advised that during the transition period customers may receive pre and post change parts, due to existing inventory of the pre changed parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
August 4, 2011: Issued initial notification.

Attachment(s):

PCN_CYER-21JXDZ485_Affected_CPN.pdf
PCN_CYER-21JXDZ485_Affected_CPN.xls
PCN_CYER-21JXDZ485_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Parts Affected

24AA1025
24FC1025
24LC1025

PCN_CYER-21JXDZ485
CATALOG_PART_NBR
24AA1025-I/SM
24AA1025T-I/SM
24FC1025-I/SM
24FC1025T-I/SM
24LC1025-E/SM
24LC1025-I/SM
24LC1025T-E/SM
24LC1025T-I/SM

QUALIFICATION PLAN

PCN#: CYER-21JXDZ485

Date:
July 21, 2011

Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.

Distribution

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Purpose: Qualification of certain catalog part numbers in the 8L SOIJ package with 8006NS die attach at MTAI assembly site.

MP code: 36003

Part No.: 24AA1025

BD No: BDE-001603 rev.01

CCB No: 1072

Package:

Type 8L SOIJ

Width or Size 208 mils

Die thickness: Top: 8 mils, Spacer: 8 mils, Bottom: 8 mils

Die size: Top/Bottom (D5AB2) 114.3 x 109.5 mils,
Spacer 47 x 89 mils

Lead frame:

Paddle size: 140 x 160

Material A194

Surface Ag plate

Process Stamp

Lead Lock No

Part Number 10100816

Wire:

Material Au

Die Attach Epoxy:

Part Number Top/Bottom: 8390A, Spacer: 8006NS

Conductive Top/Bottom: Yes, Spacer: No

Mold Compound: G600V

Reliability Test plan: See attached, STD Package Reliability Test plan on each package.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a minimum of 5 devices.
Lead Integrity	JESD22 B105	5	0	1	5	0 (No lead breakage or cracks)	5	10 leads from each of 5 parts.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C and hot temp.	45	5	1	50	0	10	For hot temp testing, pre/post test 1 lot at 85°C and 125°C (if applicable)
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020C for package type; Electrical test pre and post stress at +25°C. Perform SAM analysis using the standard sample size. MSL-1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. Pre/post test 1 lot at 85°C and 125°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning. For hot temp testing, pre/post test 1 lot at 85°C and 125°C (if applicable)
Unbiased HAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. Pre/post test 1 lot at 85°C and 125°C.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning. For hot temp testing, pre/post test 1 lot at 85°C and 125°C (if applicable).